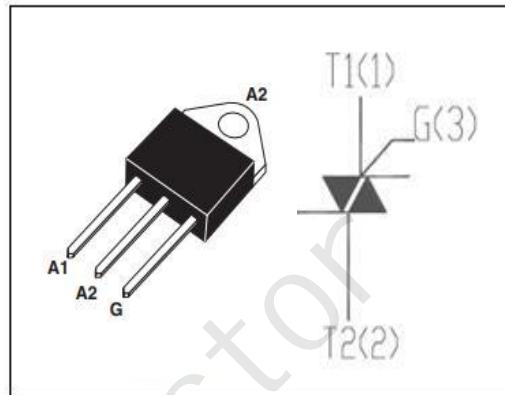


**DESCRIPTION**

- With TO-3P packaging
- Operating in 4 quadrants
- High commutation capability
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

**APPLICATIONS**

- Solid state relays; heating and cooking appliances
- Switching applications

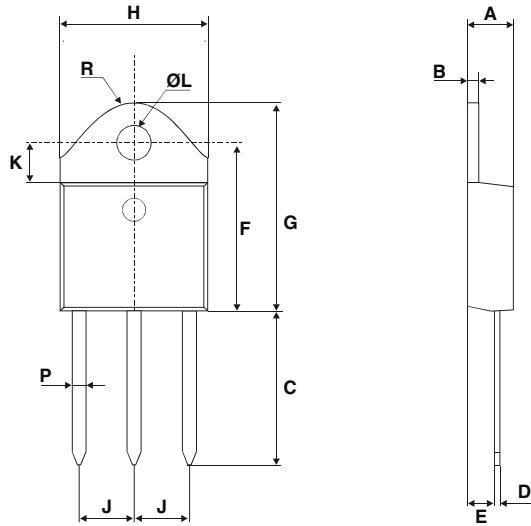

**ABSOLUTE MAXIMUM RATINGS( $T_a=25^\circ\text{C}$ )**

SYMBOL	PARAMETER	MAX	UNIT
$V_{DRM}$	Repetitive peak off-state voltage	600	V
$V_{RRM}$	Repetitive peak reverse voltage	600	V
$I_{T(RSM)}$	Average on-state current @ $T_c=80^\circ\text{C}$	40	A
$I_{TSM}$	Surge non-repetitive on-state current 50HZ 60HZ	400 420	A
$P_{G(AV)}$	Average gate power dissipation ( over any 20 ms period )	1.0	W
$T_j$	Operating junction temperature	-40~125	°C
$T_{stg}$	Storage temperature	-40~150	°C

**ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$  unless otherwise specified)**

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
$I_{RRM}$	Repetitive peak reverse current	$V_R=V_{RRM}$ Rated;			
$I_{DRM}$	Repetitive peak off-state current	$V_D=V_{DRM}$ Rated;	$T_j=25^\circ\text{C}$		mA
$V_{TM}$	On-state voltage	$I_T=60\text{A}$		1.55	V
$I_{GT}$	Gate-trigger current	$V_D = 12\text{V}; RG = 33 \Omega$	I	50	mA
			II	50	
			III	50	
			IV	100	
$V_{GT}$	Gate-trigger voltage	$V_D = 12\text{V}; RG = 33 \Omega$		1.3	V
$R_{th(j-c)}$	Junction to case	Half cycle		0.9	°C/W

## TO-3P (Insulated and non insulated) Package Mechanical Data



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.6	0.173		0.181
B	1.45		1.55	0.057		0.061
C	14.35		15.60	0.565		0.614
D	0.5		0.7	0.020		0.028
E	2.7		2.9	0.106		0.114
F	15.8		16.5	0.622		0.650
G	20.4		21.1	0.815		0.831
H	15.1		15.5	0.594		0.610
J	5.4		5.65	0.213		0.222
K	3.4		3.65	0.134		0.144
ØL	4.08		4.17	0.161		0.164
P	1.20		1.40	0.047		0.055
R		4.60			0.181	